Zener Diodes Panasonic

## **MAYS0750Y**

## Silicon epitaxial planar type

For ESD protection of high speed signal line

### ■ Features

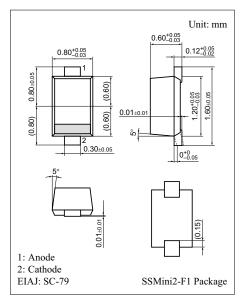
• Maintain signal cobs with low insertion loss, distortion.

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Total power dissipation *1	$P_{T}$	150	mW	
Junction temperature	$T_j$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	
Electrostatic discharge *2	ESD	±8	kV	

Note) \*1:  $P_T = 150$  mW achieved with a printed circuit board.

(C = 150 pF, R = 330  $\Omega$ , Contact discharge: 10 times)



Marking Symbol: CY

#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

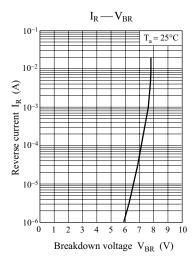
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Breakdown voltage *	V <sub>BR</sub>	$I_R = 1 \text{ mA}$	6.0	7.5		V
Reverse current	$I_R$	$V_R = 5 V$			2	μΑ
Terminal capacitance	$C_{t}$	$I_R = 0 \text{ V}, f = 1 \text{ MHz}$		0.8		pF

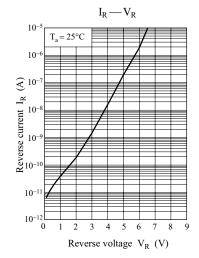
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

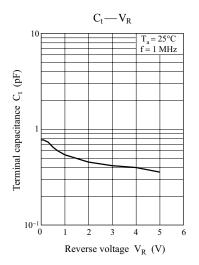
<sup>\*2:</sup> Test method: IEC61000-4-2

<sup>2. \*:</sup> V<sub>Z</sub> guaranted 20 ms after current flow.

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